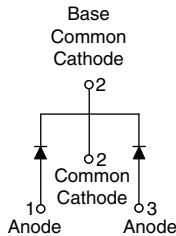
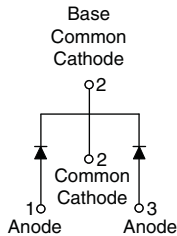


Hyperfast Rectifier, 30 A FRED Pt®


TO-263AB (D²PAK)

VS-30CTH02SPbF

TO-262AA

VS-30CTH02-1PbF

FEATURES

- Hyperfast recovery time
- Low forward voltage drop
- Low leakage current
- 175 °C operating junction temperature
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
 COMPLIANT
 HALOGEN
FREE

DESCRIPTION / APPLICATIONS

Vishay Semiconductors 200 V series are the state of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop and hyperfast recovery time.

The planar structure and the platinum doped life time control, guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in the output rectification stage of SMPS, UPS, DC/DC converters as well as freewheeling diode in low voltage inverters and chopper motor drives.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

PRODUCT SUMMARY

| Package | TO-263AB (D ² PAK), TO-262AA |
|-----------------|---|
| $I_{F(AV)}$ | 2 x 15 A |
| V_R | 200 V |
| V_F at I_F | 0.78 V |
| t_{rr} typ. | 30 ns |
| T_J max. | 175 °C |
| Diode variation | Common cathode |

ABSOLUTE MAXIMUM RATINGS

| PARAMETER | SYMBOL | TEST CONDITIONS | MAX. | UNITS |
|---|----------------|----------------------|-------------|-------|
| Peak repetitive reverse voltage | V_{RRM} | | 200 | V |
| Average rectified forward current | $I_{F(AV)}$ | per diode | 15 | A |
| | | per device | 30 | |
| Non-repetitive peak surge current | I_{FSM} | $T_C = 25\text{ °C}$ | 200 | |
| Operating junction and storage temperatures | T_J, T_{Stg} | | -65 to +175 | °C |

ELECTRICAL SPECIFICATIONS ($T_J = 25\text{ °C}$ unless otherwise specified)

| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNITS |
|-------------------------------------|---------------|--|------|------|------|---------------|
| Breakdown voltage, blocking voltage | V_{BR}, V_R | $I_R = 100\ \mu\text{A}$ | 200 | - | - | V |
| Forward voltage | V_F | $I_F = 15\text{ A}$ | - | 0.92 | 1.05 | V |
| | | $I_F = 15\text{ A}, T_J = 125\text{ °C}$ | - | 0.78 | 0.85 | |
| Reverse leakage current | I_R | $V_R = V_R$ rated | - | - | 10 | μA |
| | | $T_J = 125\text{ °C}, V_R = V_R$ rated | - | 5 | 300 | |
| Junction capacitance | C_T | $V_R = 200\text{ V}$ | - | 57 | - | pF |
| Series inductance | L_S | Measured lead to lead 5 mm from package body | - | 8 | - | nH |



| DYNAMIC RECOVERY CHARACTERISTICS (T _C = 25 °C unless otherwise specified) | | | | | | | |
|--|------------------|---|---|------|------|-------|---|
| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNITS | |
| Reverse recovery time | t _{rr} | I _F = 1 A, dI _F /dt = 50 A/μs, V _R = 30 V | - | - | 35 | ns | |
| | | I _F = 1 A, dI _F /dt = 100 A/μs, V _R = 30 V | - | - | 30 | | |
| | | T _J = 25 °C | I _F = 15 A dI _F /dt = 200 A/μs V _R = 160 V | - | 26 | | - |
| | | T _J = 125 °C | | - | 40 | | - |
| Peak recovery current | I _{RRM} | T _J = 25 °C | - | 2.8 | - | A | |
| | | T _J = 125 °C | - | 6.0 | - | | |
| Reverse recovery charge | Q _{rr} | T _J = 25 °C | - | 37 | - | nC | |
| | | T _J = 125 °C | - | 120 | - | | |

| THERMAL - MECHANICAL SPECIFICATIONS | | | | | |
|--|-----------------------------------|--|------|------------|------------------------|
| PARAMETER | SYMBOL | MIN. | TYP. | MAX. | UNITS |
| Maximum junction and storage temperature range | T _J , T _{Stg} | -65 | - | 175 | °C |
| Thermal resistance, junction to case per diode | R _{thJC} | - | - | 1.1 | °C/W |
| Weight | | - | 2.0 | - | g |
| | | - | 0.07 | - | oz. |
| Mounting torque | | 6.0 (5.0) | - | 12 (10) | kgf · cm (lbf · in) |
| Marking device | | Case style TO-263AB (D ² PAK) | | 30CTH02S | |
| | | Case style TO-262 | | 30CTH02-1 | |

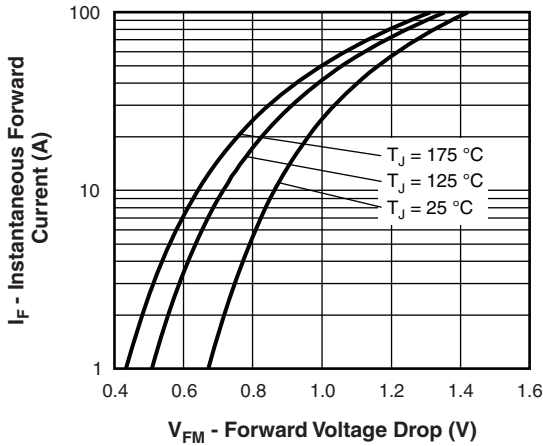


Fig. 1 - Maximum Forward Voltage Drop Characteristics

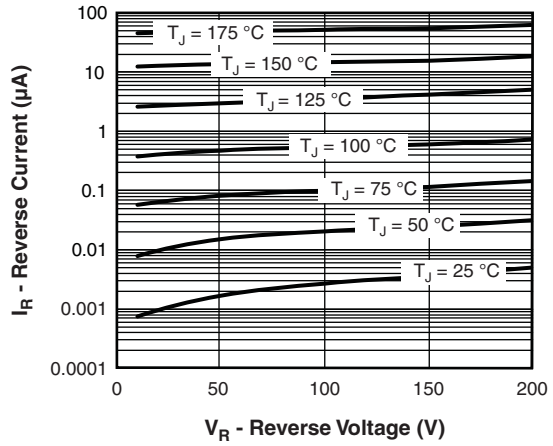


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

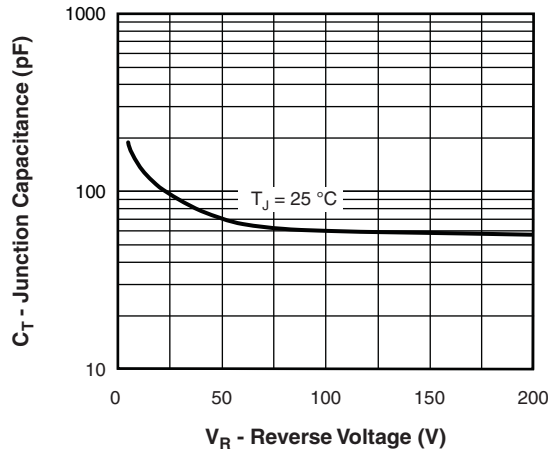


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

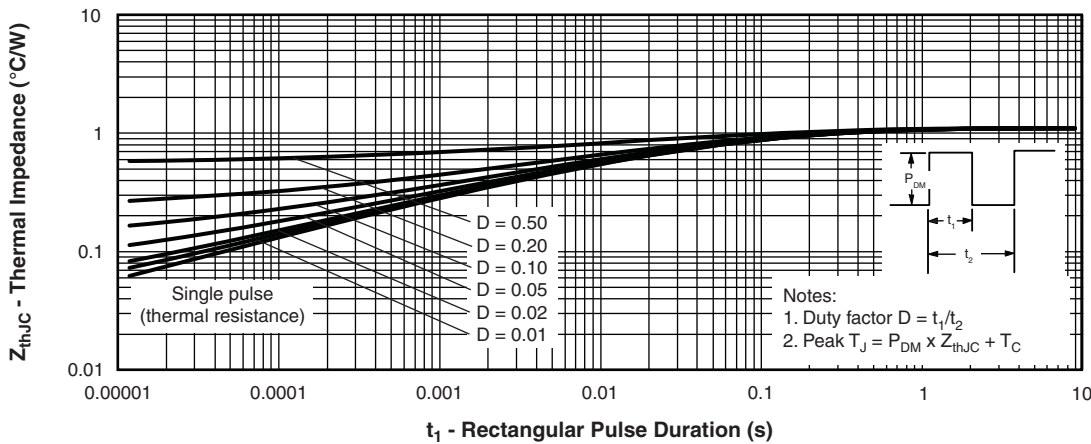


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

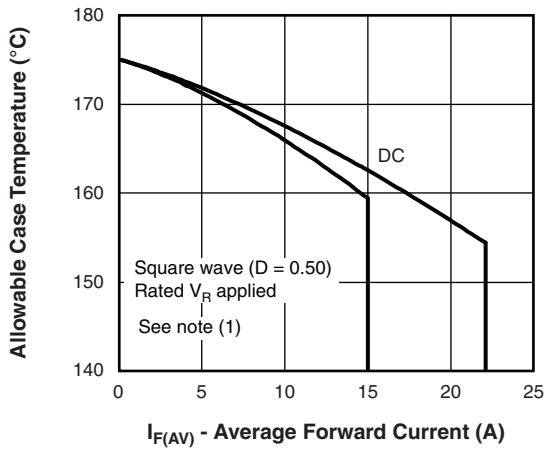


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

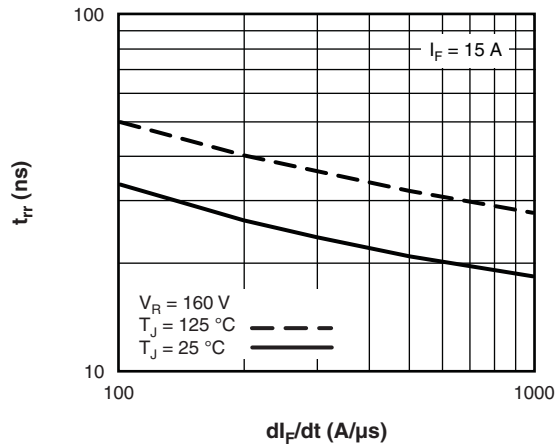


Fig. 7 - Typical Reverse Recovery Time vs. di/dt

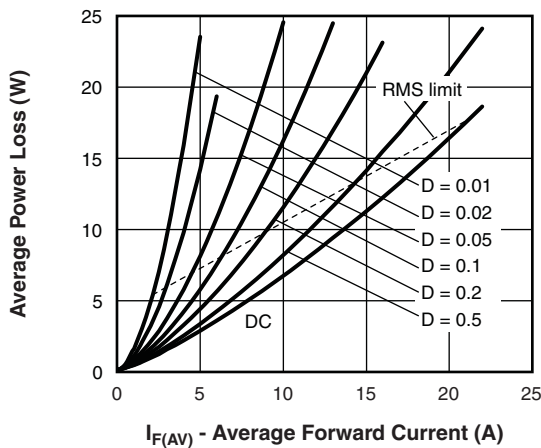


Fig. 6 - Forward Power Loss Characteristics

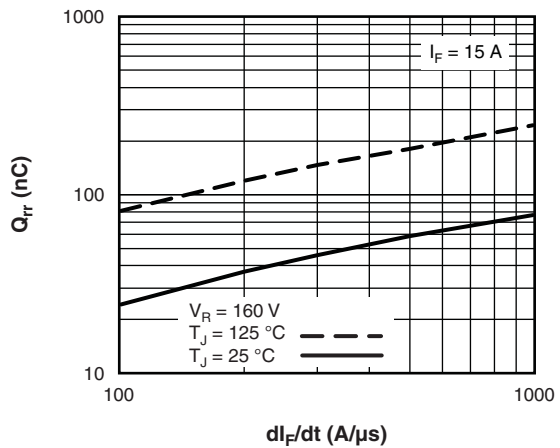


Fig. 8 - Typical Stored Charge vs. di/dt

Note

- (1) Formula used: $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$;
- P_d = Forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6);
- P_{dREV} = Inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at V_{R1} = Rated V_R

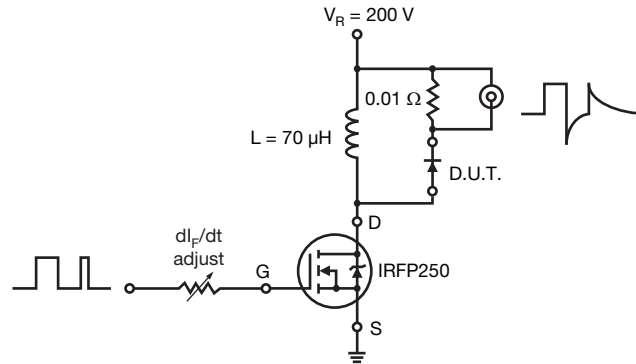
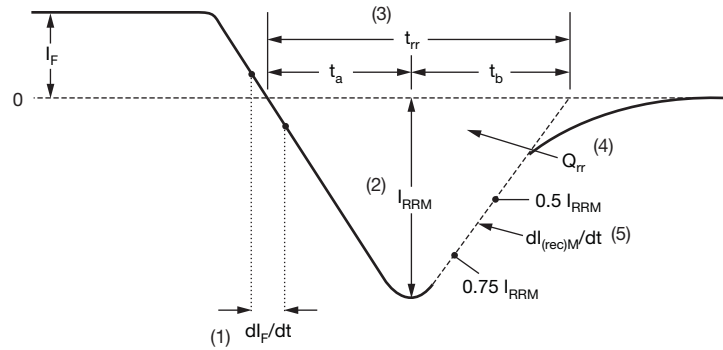


Fig. 9 - Reverse Recovery Parameter Test Circuit

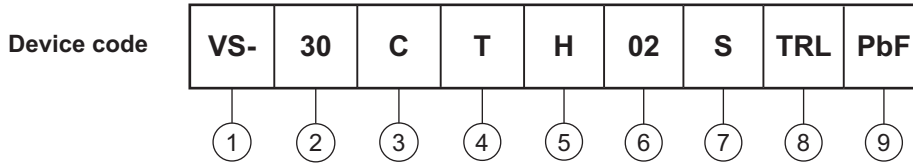


- | | |
|---|---|
| <p>(1) di_F/dt - rate of change of current through zero crossing</p> <p>(2) I_{RRM} - peak reverse recovery current</p> <p>(3) t_{rr} - reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through $0.75 I_{RRM}$ and $0.50 I_{RRM}$ extrapolated to zero current.</p> | <p>(4) Q_{rr} - area under curve defined by t_{rr} and I_{RRM}</p> $Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$ <p>(5) $dl_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}</p> |
|---|---|

Fig. 10 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE



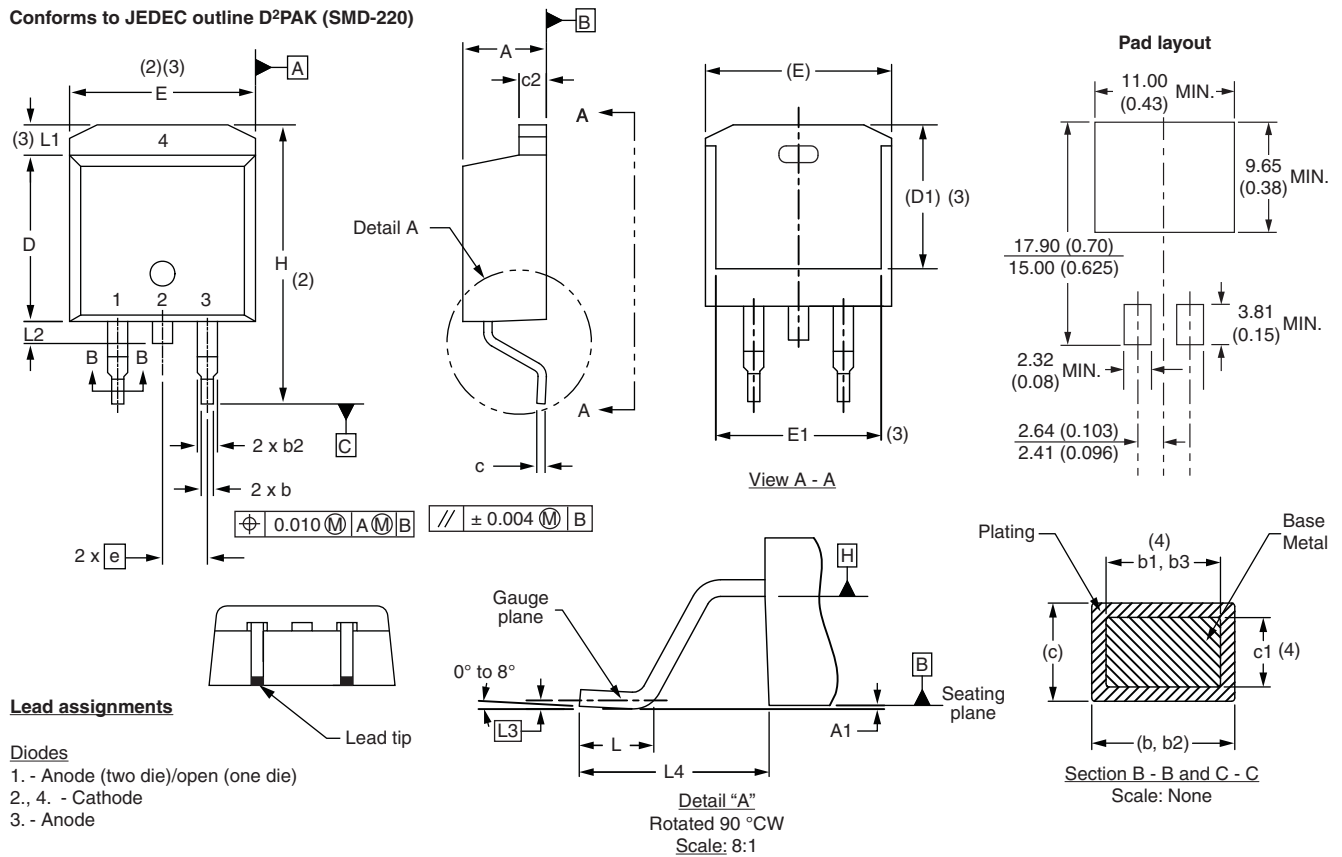
- 1** - Vishay Semiconductors product
- 2** - Current rating (30 A)
- 3** - C = common cathode
- 4** - T = TO-220, D²PAK
- 5** - H = hyperfast rectifier
- 6** - Voltage rating (02 = 200 V)
- 7** -
 - S = D²PAK
 - -1 = TO-262
- 8** -
 - None = tube (50 pieces)
 - TRL = tape and reel (left oriented, for D²PAK package)
 - TRR = tape and reel (right oriented, for D²PAK package)
- 9** - PbF = lead (Pb)-free

| LINKS TO RELATED DOCUMENTS | |
|----------------------------|--|
| Dimensions | www.vishay.com/doc?95014 |
| Part marking information | www.vishay.com/doc?95008 |
| Packaging information | www.vishay.com/doc?95032 |

D²PAK, TO-262

DIMENSIONS - D²PAK in millimeters and inches

Conforms to JEDEC outline D²PAK (SMD-220)



| SYMBOL | MILLIMETERS | | INCHES | | NOTES |
|--------|-------------|-------|--------|-------|-------|
| | MIN. | MAX. | MIN. | MAX. | |
| A | 4.06 | 4.83 | 0.160 | 0.190 | |
| A1 | 0.00 | 0.254 | 0.000 | 0.010 | |
| b | 0.51 | 0.99 | 0.020 | 0.039 | |
| b1 | 0.51 | 0.89 | 0.020 | 0.035 | 4 |
| b2 | 1.14 | 1.78 | 0.045 | 0.070 | |
| b3 | 1.14 | 1.73 | 0.045 | 0.068 | 4 |
| c | 0.38 | 0.74 | 0.015 | 0.029 | |
| c1 | 0.38 | 0.58 | 0.015 | 0.023 | 4 |
| c2 | 1.14 | 1.65 | 0.045 | 0.065 | |
| D | 8.51 | 9.65 | 0.335 | 0.380 | 2 |

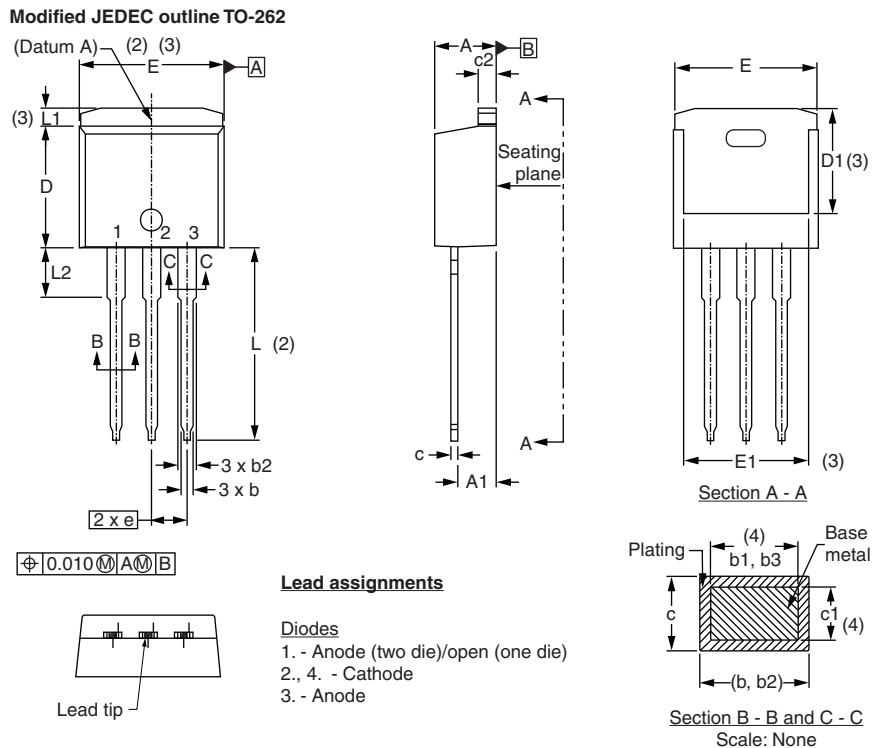
| SYMBOL | MILLIMETERS | | INCHES | | NOTES |
|--------|-------------|-------|-----------|-------|-------|
| | MIN. | MAX. | MIN. | MAX. | |
| D1 | 6.86 | 8.00 | 0.270 | 0.315 | 3 |
| E | 9.65 | 10.67 | 0.380 | 0.420 | 2, 3 |
| E1 | 7.90 | 8.80 | 0.311 | 0.346 | 3 |
| e | 2.54 BSC | | 0.100 BSC | | |
| H | 14.61 | 15.88 | 0.575 | 0.625 | |
| L | 1.78 | 2.79 | 0.070 | 0.110 | |
| L1 | - | 1.65 | - | 0.066 | 3 |
| L2 | 1.27 | 1.78 | 0.050 | 0.070 | |
| L3 | 0.25 BSC | | 0.010 BSC | | |
| L4 | 4.78 | 5.28 | 0.188 | 0.208 | |

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch

- (7) Outline conforms to JEDEC outline TO-263AB

DIMENSIONS - TO-262 in millimeters and inches



| SYMBOL | MILLIMETERS | | INCHES | | NOTES |
|--------|-------------|-------|-----------|-------|-------|
| | MIN. | MAX. | MIN. | MAX. | |
| A | 4.06 | 4.83 | 0.160 | 0.190 | |
| A1 | 2.03 | 3.02 | 0.080 | 0.119 | |
| b | 0.51 | 0.99 | 0.020 | 0.039 | |
| b1 | 0.51 | 0.89 | 0.020 | 0.035 | 4 |
| b2 | 1.14 | 1.78 | 0.045 | 0.070 | |
| b3 | 1.14 | 1.73 | 0.045 | 0.068 | 4 |
| c | 0.38 | 0.74 | 0.015 | 0.029 | |
| c1 | 0.38 | 0.58 | 0.015 | 0.023 | 4 |
| c2 | 1.14 | 1.65 | 0.045 | 0.065 | |
| D | 8.51 | 9.65 | 0.335 | 0.380 | 2 |
| D1 | 6.86 | 8.00 | 0.270 | 0.315 | 3 |
| E | 9.65 | 10.67 | 0.380 | 0.420 | 2, 3 |
| E1 | 7.90 | 8.80 | 0.311 | 0.346 | 3 |
| e | 2.54 BSC | | 0.100 BSC | | |
| L | 13.46 | 14.10 | 0.530 | 0.555 | |
| L1 | - | 1.65 | - | 0.065 | 3 |
| L2 | 3.56 | 3.71 | 0.140 | 0.146 | |

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum) and D1 (minimum) where dimensions derived the actual package outline



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